

## APM7330J-VB Datasheet

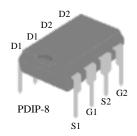
## Dual N-Channel 30 V (D-S) 175 °C MOSFET

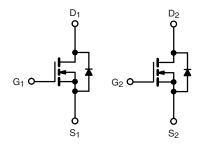
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	30			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.010			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.011			
I <sub>D</sub> (A)	8			
Configuration	Dual			

#### **FEATURES**

- TrenchFET® Power MOSFET
- $\bullet$  100 %  $R_g$  and UIS Tested







N-Channel MOSFET N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			30	V	
Gate-Source Voltage	urce Voltage		± 20		
Continuous Drain Current	T <sub>C</sub> = 25 °C <sup>a</sup>	1	8		
	T <sub>C</sub> = 125 °C	Ι <sub>D</sub>	8		
Continuous Source Current (Diode Conduction)		Is	3.5	Α	
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	32		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	34		
Single Pulse Avalanche Energy	L = 0.1 min	E <sub>AS</sub>	58	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	D	3.9	W	
	T <sub>C</sub> = 125 °C	$P_{D}$	1.3	VV	
Operating Junction and Storage Temperature Range	je	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount <sup>b</sup>	$R_{thJA}$	120	°C/W	
Junction-to-Foot (Drain)		$R_{thJF}$	38	C/ VV	

#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. When mounted on 1" square PCB (FR-4 material).

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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static	L			l			
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		30	-	-	.,
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		2.0	2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 30 V	-	-	1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 30 V, T <sub>J</sub> = 125 °C	-	-	50	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 30 V, T <sub>J</sub> = 175 °C	-	-	250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	V <sub>DS</sub> ≥ 5 V	30	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 15 A	-	0.0100	-	Ω
Dunin Course On State Desistance		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 15 A, T <sub>J</sub> = 125 °C	-	0.0176	-	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 15 A, T <sub>J</sub> = 175 °C	-	0.0210	-	
	$V_{GS} = 4.5 \text{ V}$ $I_{D} = 14 \text{ A}$	-	0.0110	-			
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A		-	67	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		= 0 V V <sub>DS</sub> = 15 V, f = 1 MHz	-	1893	2367	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	396	495	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	139	173	
Total Gate Charge <sup>c</sup>	Qg			-	31.5	47	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$V_{DS} = 20 \text{ V}, I_{D} = 11 \text{ A}$	-	6.4	-	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	4	-	
Gate Resistance	R <sub>g</sub>	f = 1 MHz		2.45	4.91	7.5	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	$V_{DD}$ = 15 V, $R_L$ = 1.67 $\Omega$ $I_D \cong$ 9 A, $V_{GEN}$ = 10 V, $R_g$ = 1 $\Omega$		-	10	15	- ns
Rise Time <sup>c</sup>	t <sub>r</sub>			-	11	17	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	34	51	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	8	12	
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	32	Α
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 8 A, V <sub>GS</sub> = 0 V		_	0.76	1.2	V

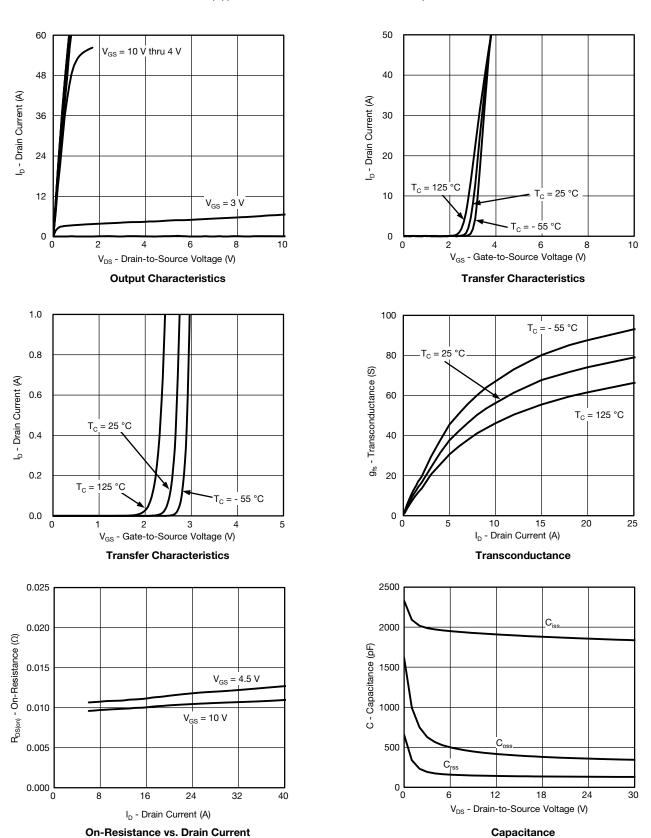
#### Notes

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

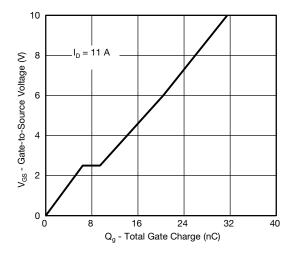


### **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

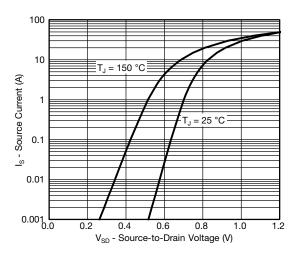




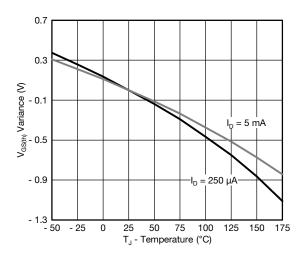
### TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



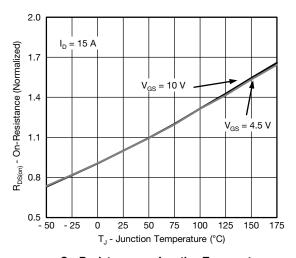
**Gate Charge** 



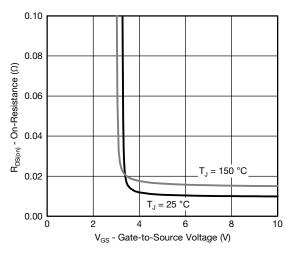
**Source Drain Diode Forward Voltage** 



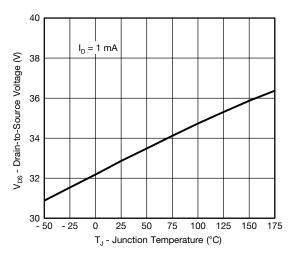
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



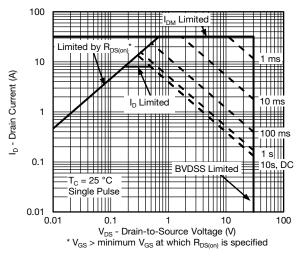
On-Resistance vs. Gate-to-Source Voltage



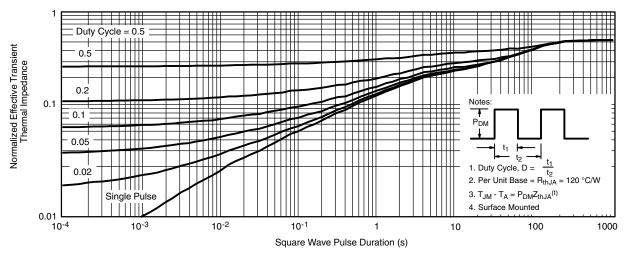
**Drain Source Breakdown vs. Junction Temperature** 



### **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



Safe Operating Area



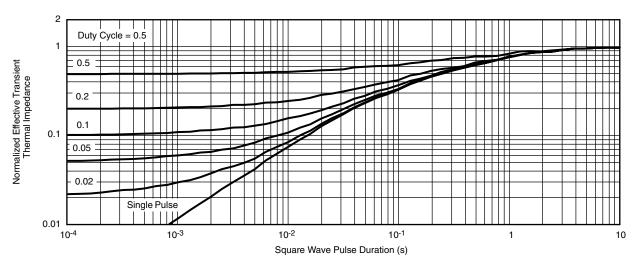
Normalized Thermal Transient Impedance, Junction-to-Ambient

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### THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



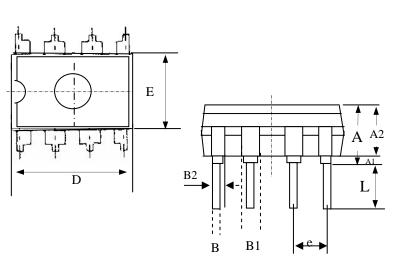
#### Normalized Thermal Transient Impedance, Junction-to-Foot

#### Note

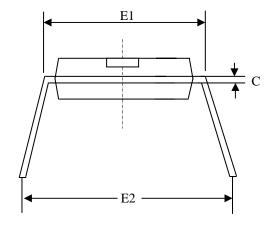
- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



# Package Outline: PDIP-8



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A	3.60	4.50	5.40
<b>A1</b>	0.38		
<b>A2</b>	2.90	3.95	5.00
В	0.36	0.46	0.56
<b>B</b> 1	1.10	1.45	1.80
<b>B2</b>	0.76	0.98	1.20
C	0.20	0.28	0.36
D	9.00	9.60	10.20
E	6.10	6.65	7.20
<b>E</b> 1	7.62	7.94	8.26
<b>E2</b>	8.30	9.65	11.00
e	2.540 BSC		
L	3.18		



- 1.All Dimensions Are in Millimeters.
- 2.Dimension Does Not Include Mold Protrusions.



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